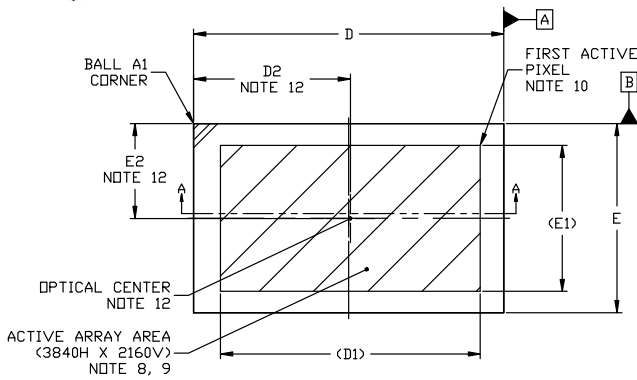
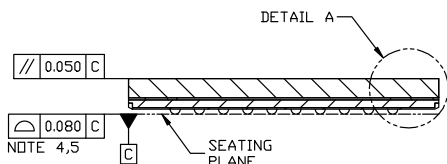


ODCSP59 6.41x3.91x0.63, 0.50P
CASE 570AY
ISSUE O

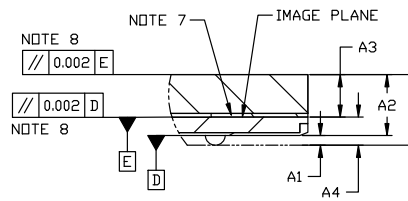
DATE 15 NOV 2023



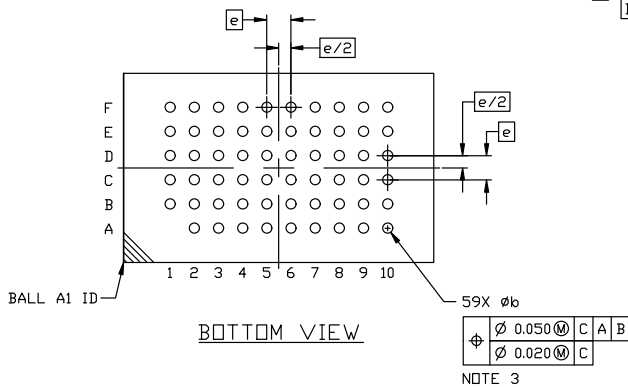
TOP VIEW



SECTION A-A

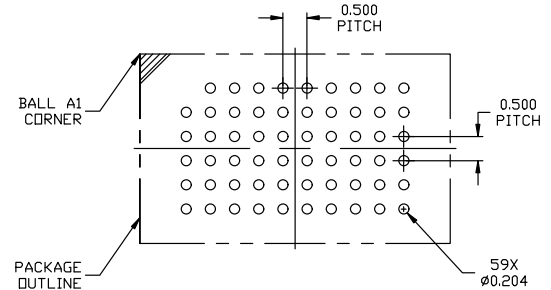


DETAIL "A"
SCALE 2:1



BOTTOM VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	----	----	0.762
A1	0.081	0.101	0.121
A2	0.631 REF.		
A3	0.425	0.440	0.455
A4	0.252	0.292	0.332
b	0.184	0.204	0.224
D	6.392	6.417	6.442
D1	5.376 REF.		
D2	3.218	3.243	3.268
E	3.889	3.914	3.939
E1	3.024 REF.		
E2	1.937	1.962	1.987
e	0.500 BSC		



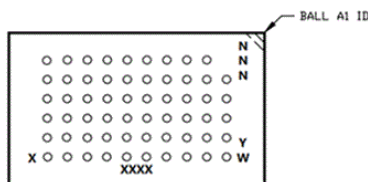
RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.
- SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
- AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.040 THICKNESS.
- PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
- MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS $\pm 0.1^\circ$.
- REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
- PACKAGE CENTER (X, Y) = (0.000, 0.000).
- OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.035, -0.005).

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
Y = Year
W = Work Week
NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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